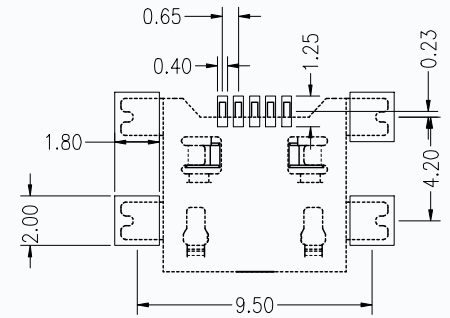
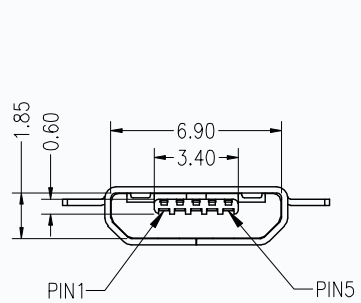
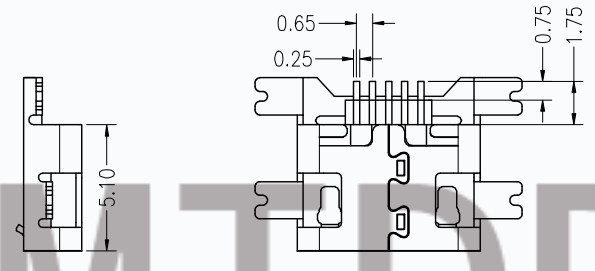
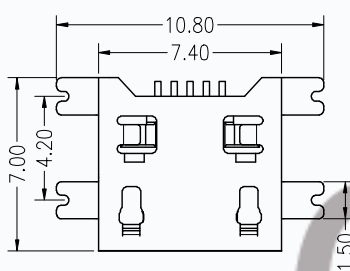
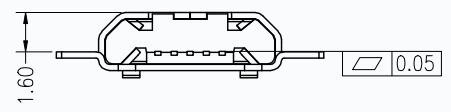


REV.	MODIFICATION	ECN No.	NAME	DATE
A	新版发行		ERIC	2018.06.10



RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05

NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC FLAMMABILITY RATING UL94-0
 - CONTACT: COPPERY ALLOY T=0.20MM
 - SHELL: COPPERY ALLOY T=0.25MM
- FINISH:
 - CONTACT:
 - 1U" MIN. PLATED ON CONTACT AREA
 - G/F PLATING ON SOLDER TAIL AREA
 - 50~80U" NICKEL UNDERPLATING OVERALL
 - SHELL:
 - 80~120U" MATTER TIN PLATING ALL
 - 50~80U" NICKEL UNDERPLATING OVERALL
- SPECIFICATION:
 - CURRENT RATING: 0.5A(2.3.4CONTACT)/1.8A (1.5CONTACT) MAX.
 - VOLTAGE: 30 VAC
 - TEMPERATURE RANGE: -30°C~85°C
 - CONTACT RESISTANCE: 30 MILLIONHM MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 250VAC
 - INSULATION RESISTANCE: 100 MEGOHMS MIN

UNLESS OTHERWISE SPECIFIED TOLERANCES		CMTDDZ 东莞市田都科技有限公司 Dongguan TianDu Technology Co. Ltd.			
.X: ±0.15	.X': ±1.5'	TITLE:	MICRO USB 2.0 5P SMT 沉板贴片直边1.60H母座		
.XX: ±0.10	.XX': ±1.0'	APPD.: ERIC	MOULD NO.:	T10-05CB15	
.XXX: ±0.05	.XXX': ±0.5'	MAT'L.: SEE NOTES	CHKD.:	DWG. NO.:	PAGE: 1/1
FINISH:		DR.:	UNIT:	SCALE: 1:1	REV.: A